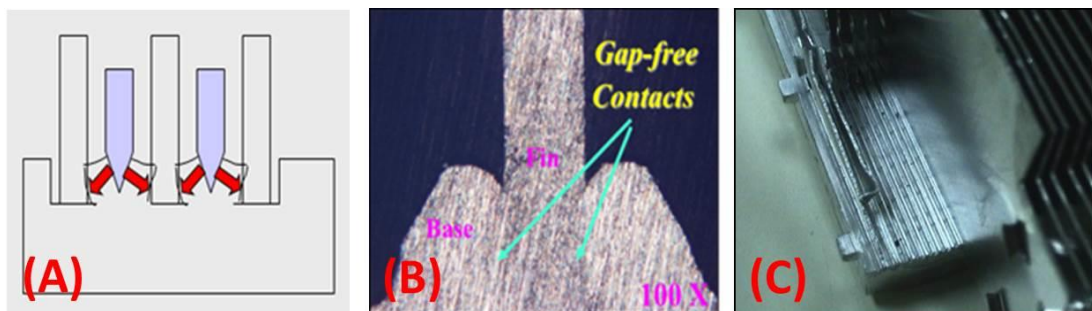


Base/Fin Swaging

Flat Base Heat Sink

Base/fin swaging process is to plastically deform the groove walls formed on a flat base via a stamping technique (Fig. A). Swaged base/fin interface is extremely intimate (Fig. B), therefore has very high joint strength (Fig. C) and low thermal interface resistance. Without Ni-plating and solder paste, swaged heat sink has best performance/cost merit with 100% green to the environment.



Base/fin swaging is the most basic and common process used for solderless heat sink such as DT, VGA, Power, Telecom, ...etc. The heatsink can be ranged from as small as mobile NB/tablet (Fig. D) to as big as power applications(Fig. E).

